L Number	Hits	Search Text	DB	Time stamp
1	12	257/677 and solder ADJ BALL	USPAT;	2004/08/07 13:23
		·	US-PGPUB;	
			EPO; JPO;	
			IBM_TDB	
2	392	257/678 and solder ADJ BALL	USPAT;	2004/08/07 13:45
		·	US-PGPUB;	
			EPO; JPO;	
			IBM_TDB	
3	97	257/679 and solder ADJ BALL	USPAT;	2004/08/07 13:49
			US-PGPUB;	
			EPO; JPO;	
		•	IBM_TDB	
4	80	257/680 and solder ADJ BALL	USPAT;	2004/08/07 13:52
			US-PGPUB;	
			EPO; JPO;	
			IBM_TDB	
5	482	257/698 and solder ADJ BALL	USPAT;	2004/08/07 13:52
			US-PGPUB;	
			EPO; JPO;	
		(IIC+07C+2II) PN	IBM_TDB	2004/00/05 17:40
-	1	("6187612").PN.	USPAT;	2004/08/05 17:48
			US-PGPUB;	
			EPO; JPO;	
	1	"20020027441"	IBM_TDB USPAT;	2004/08/05 17:55
-	1	20020027441	US-PGPUB;	2004/06/03 17.33
			EPO; JPO;	
			IBM_TDB	
_	65	lead adj frame and protrusion and solder adj ball	USPAT;	2004/08/05 18:25
		lead day manie and production and solder day sain	US-PGPUB;	200 1,00,00 20:20
	a		EPO; JPO;	
			IBM_TDB	
_	371	257/666 and solder ADJ BALL	USPAT;	2004/08/05 18:40
		,	US-PGPUB;	, .
			EPO; JPO;	
			IBM_TDB	
-	13	("4069000" "5244838" "5293072" "5635755" "5656863"	USPAT	2004/08/05 18:30
		"5783461" "5847455" "5893724" "5923954" "5925934"		
		"5930603" "5982026" "5989935").PN.		
-	78	257/667 and solder ADJ BALL	USPAT;	2004/08/05 18:42
1			US-PGPUB;	
			EPO; JPO;	
	274	3E7/669 and coldor ADI PALL	IBM_TDB	2004/00/06 20:50
-	371	257/668 and solder ADJ BALL	USPAT; US-PGPUB;	2004/08/06 20:50
			EPO; JPO;	
			IBM_TDB	
_	113	257/673 and solder ADJ BALL	USPAT;	2004/08/06 20:55
	115	207, 0.0 did dolder 1100 brills	US-PGPUB;	
			EPO; JPO;	
			IBM_TDB	
-	196	257/676 and solder ADJ BALL	USPAT;	2004/08/07 13:21
		·	US-PGPUB;	
			EPO; JPO;	
L			IBM_TDB	